

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Blackshear et al.

Serial No.: 10/056,256

Group Art Unit: 2811

Filed: January 24, 2002

Examiner: Unknown

For: VERTICALLY STACKED MEMORY CHIPS IN FBGA PACKAGES


Assistant Commissioner of Patents
Washington, D.C. 20231

SUBMISSION OF FORMAL DRAWINGS

Sir:

Submitted herewith is one (1) sheet of formal drawings comprising Figs. 1-3 for the above-referenced patent application. Acknowledgment of receipt is respectfully requested. Please substitute these formal drawings for the drawings which were filed with the application.

Respectfully Submitted,



Frederick W. Gibb, III
Reg. No. 37,629

Date:

3/27/02

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2811

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Applicant(s): **Blackshear et al.**

Docket No.

FIS9-2000-0273-US1

Serial No.
10/056,256

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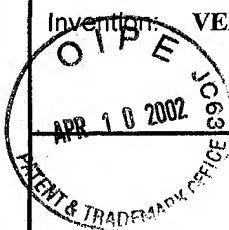
Examiner

Unknown

Group Art Unit

2811

Invention: **VERTICALLY STACKED MEMORY CHIPS IN FBGA PACKAGES**



I hereby certify that this Submission of Formal Drawings

(Identify type of correspondence)

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